

DATA SHEET

BF245A; BF245B; BF245C N-channel silicon field-effect transistors

Product specification
Supersedes data of April 1995
File under Discrete Semiconductors, SC07

1996 Jul 30

N-channel silicon field-effect transistors

BF245A; BF245B; BF245C

FEATURES

- Interchangeability of drain and source connections
- Frequencies up to 700 MHz.

APPLICATIONS

- LF, HF and DC amplifiers.

DESCRIPTION

General purpose N-channel symmetrical junction field-effect transistors in a plastic TO-92 variant package.

CAUTION

The device is supplied in an antistatic package. The gate-source input must be protected against static discharge during transport or handling.

PINNING

| PIN | SYMBOL | DESCRIPTION |
|-----|--------|-------------|
| 1 | d | drain |
| 2 | s | source |
| 3 | g | gate |

MAM257

Fig.1 Simplified outline (TO-92 variant) and symbol.

QUICK REFERENCE DATA

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-------------|---|--|--------------|-------------|-----------------|----------------|
| V_{DS} | drain-source voltage | | – | – | ± 30 | V |
| V_{GSoff} | gate-source cut-off voltage | $I_D = 10\text{ nA}$; $V_{DS} = 15\text{ V}$ | –0.25 | – | –8 | V |
| V_{GSO} | gate-source voltage | open drain | – | – | –30 | V |
| I_{DSS} | drain current BF245A BF245B BF245C | $V_{DS} = 15\text{ V}$; $V_{GS} = 0$ | 2 6 12 | – – – | 6.5 15 25 | mA mA mA |
| P_{tot} | total power dissipation | $T_{amb} = 75\text{ }^{\circ}\text{C}$ | – | – | 300 | mW |
| $ y_{fs} $ | forward transfer admittance | $V_{DS} = 15\text{ V}$; $V_{GS} = 0$; $f = 1\text{ kHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$ | 3 | – | 6.5 | mS |
| C_{rs} | reverse transfer capacitance | $V_{DS} = 20\text{ V}$; $V_{GS} = -1\text{ V}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$ | – | 1.1 | – | pF |

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|-----------|--------------------------------|---|------|----------|------|
| V_{DS} | drain-source voltage | | – | ± 30 | V |
| V_{GDO} | gate-drain voltage | open source | – | –30 | V |
| V_{GSO} | gate-source voltage | open drain | – | –30 | V |
| I_D | drain current | | – | 25 | mA |
| I_G | gate current | | – | 10 | mA |
| P_{tot} | total power dissipation | up to $T_{amb} = 75\text{ °C}$; | – | 300 | mW |
| | | up to $T_{amb} = 90\text{ °C}$; note 1 | – | 300 | mW |
| T_{stg} | storage temperature | | –65 | +150 | °C |
| T_j | operating junction temperature | | – | 150 | °C |

Note

- Device mounted on a printed-circuit board, minimum lead length 3 mm, mounting pad for drain lead minimum 10 mm × 10 mm.

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------|---|-------------|-------|------|
| $R_{th\ j-a}$ | thermal resistance from junction to ambient | in free air | 250 | K/W |
| | thermal resistance from junction to ambient | | 200 | K/W |

STATIC CHARACTERISTICS

$T_j = 25\text{ °C}$; unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|---------------|-------------------------------|--|-------|------|---------------|
| $V_{(BR)GSS}$ | gate-source breakdown voltage | $I_G = -1\text{ }\mu\text{A}$; $V_{DS} = 0$ | –30 | – | V |
| V_{GSoff} | gate-source cut-off voltage | $I_D = 10\text{ nA}$; $V_{DS} = 15\text{ V}$ | –0.25 | –8.0 | V |
| V_{GS} | gate-source voltage | $I_D = 200\text{ }\mu\text{A}$; $V_{DS} = 15\text{ V}$ | –0.4 | –2.2 | V |
| | BF245A | | –1.6 | –3.8 | V |
| | BF245B | | –3.2 | –7.5 | V |
| I_{DSS} | drain current | $V_{DS} = 15\text{ V}$; $V_{GS} = 0$; note 1 | | | |
| | BF245A | | 2 | 6.5 | mA |
| | BF245B | | 6 | 15 | mA |
| I_{GSS} | gate cut-off current | $V_{GS} = -20\text{ V}$; $V_{DS} = 0$ | – | –5 | nA |
| | | $V_{GS} = -20\text{ V}$; $V_{DS} = 0$; $T_j = 125\text{ °C}$ | – | –0.5 | μA |

Note

- Measured under pulse conditions: $t_p = 300\text{ }\mu\text{s}$; $\delta \leq 0.02$.

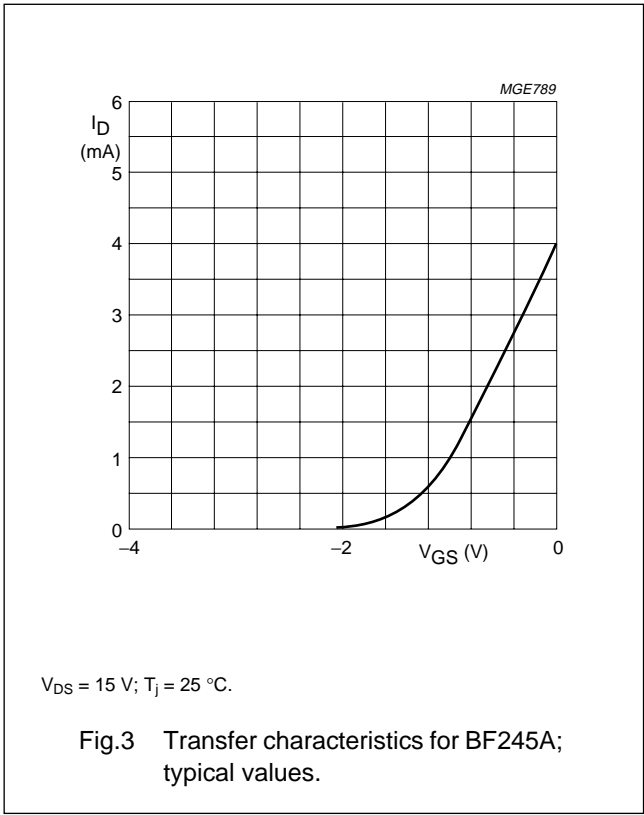
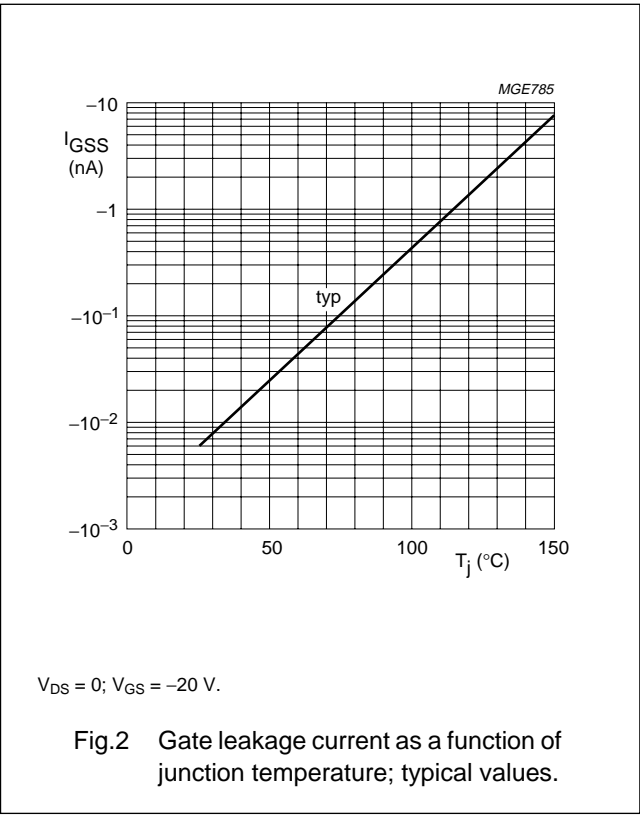
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DYNAMIC CHARACTERISTICS

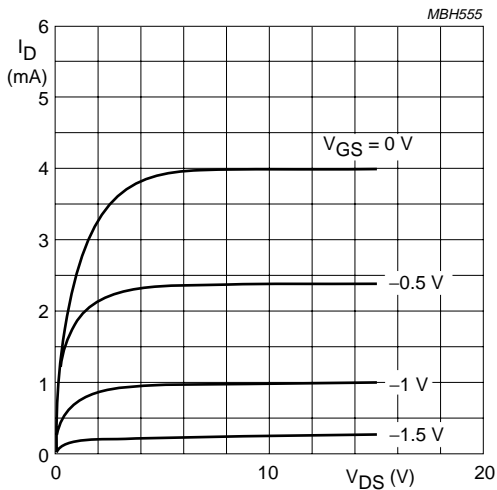
Common source; $T_{\text{amb}} = 25\text{ }^{\circ}\text{C}$; unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-------------------|------------------------------|--|------|------|------|---------------|
| C_{is} | input capacitance | $V_{\text{DS}} = 20\text{ V}$; $V_{\text{GS}} = -1\text{ V}$; $f = 1\text{ MHz}$ | – | 4 | – | pF |
| C_{rs} | reverse transfer capacitance | $V_{\text{DS}} = 20\text{ V}$; $V_{\text{GS}} = -1\text{ V}$; $f = 1\text{ MHz}$ | – | 1.1 | – | pF |
| C_{os} | output capacitance | $V_{\text{DS}} = 20\text{ V}$; $V_{\text{GS}} = -1\text{ V}$; $f = 1\text{ MHz}$ | – | 1.6 | – | pF |
| g_{is} | input conductance | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 200\text{ MHz}$ | – | 250 | – | μS |
| g_{os} | output conductance | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 200\text{ MHz}$ | – | 40 | – | μS |
| $ y_{\text{fs}} $ | forward transfer admittance | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 1\text{ kHz}$ | 3 | – | 6.5 | mS |
| | | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 200\text{ MHz}$ | – | 6 | – | mS |
| $ y_{\text{rs}} $ | reverse transfer admittance | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 200\text{ MHz}$ | – | 1.4 | – | mS |
| $ y_{\text{os}} $ | output admittance | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 1\text{ kHz}$ | – | 25 | – | μS |
| f_{gfs} | cut-off frequency | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $g_{\text{fs}} = 0.7$ of its value at 1 kHz | – | 700 | – | MHz |
| F | noise figure | $V_{\text{DS}} = 15\text{ V}$; $V_{\text{GS}} = 0$; $f = 100\text{ MHz}$; $R_{\text{G}} = 1\text{ k}\Omega$ (common source); input tuned to minimum noise | – | 1.5 | – | dB |



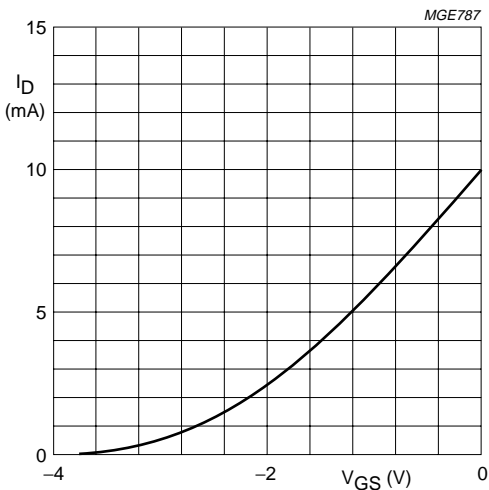
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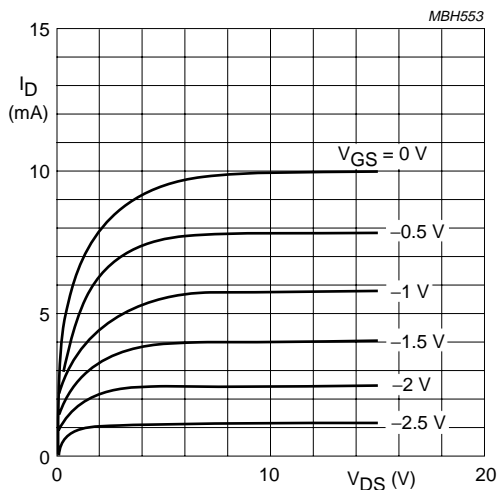
$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$.

Fig.4 Output characteristics for BF245A; typical values.



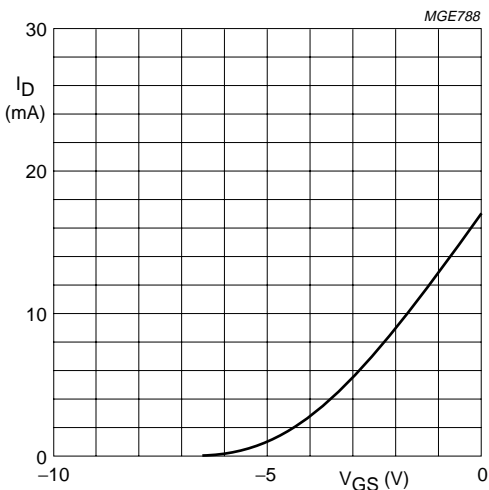
$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$.

Fig.5 Transfer characteristics for BF245B; typical values.



$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$.

Fig.6 Output characteristics for BF245B; typical values.

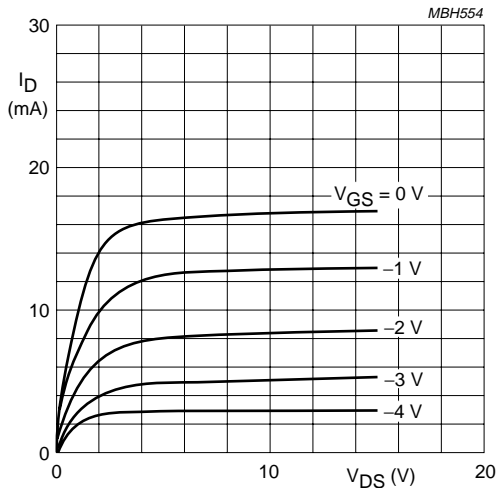


$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^\circ\text{C}$.

Fig.7 Transfer characteristics for BF245C; typical values.

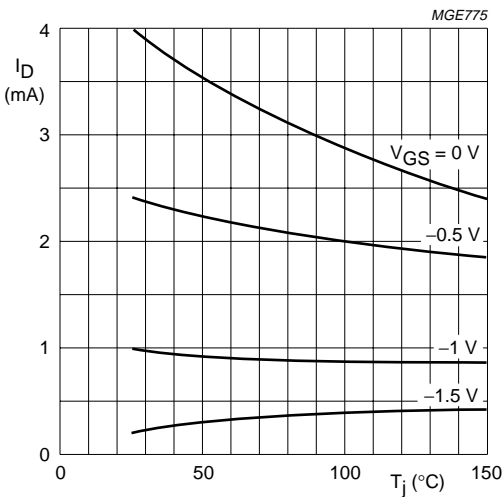
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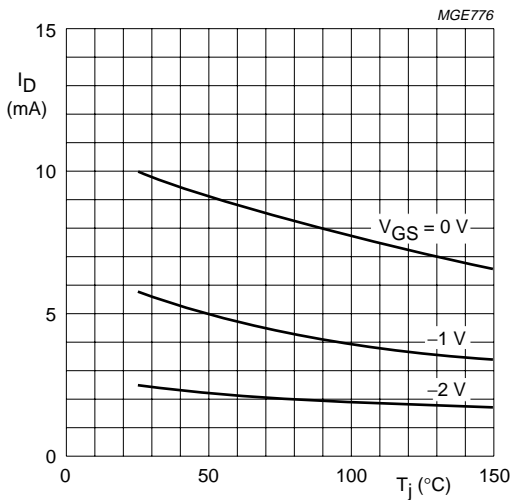
$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$.

Fig.8 Output characteristics for BF245C; typical values.



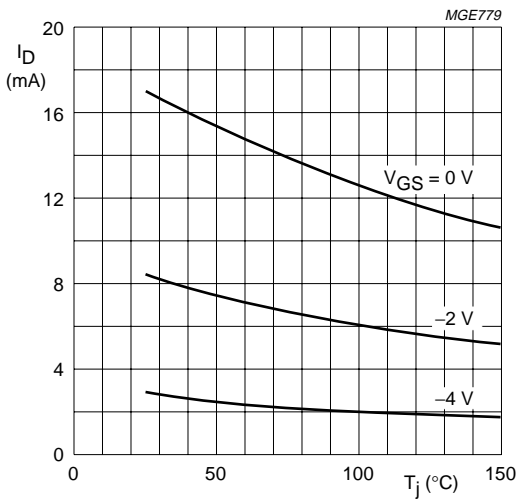
$V_{DS} = 15\text{ V}$.

Fig.9 Drain current as a function of junction temperature; typical values for BF245A.



$V_{DS} = 15\text{ V}$.

Fig.10 Drain current as a function of junction temperature; typical values for BF245B.

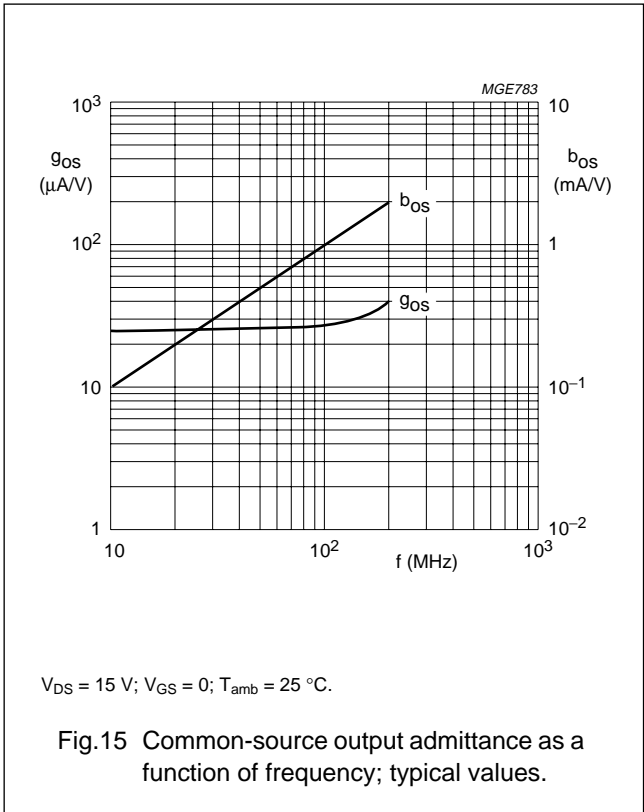
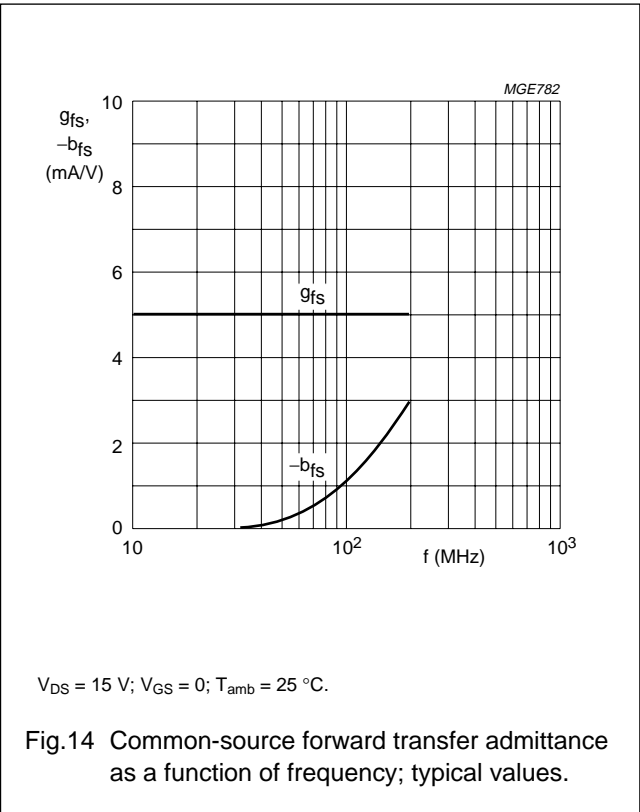
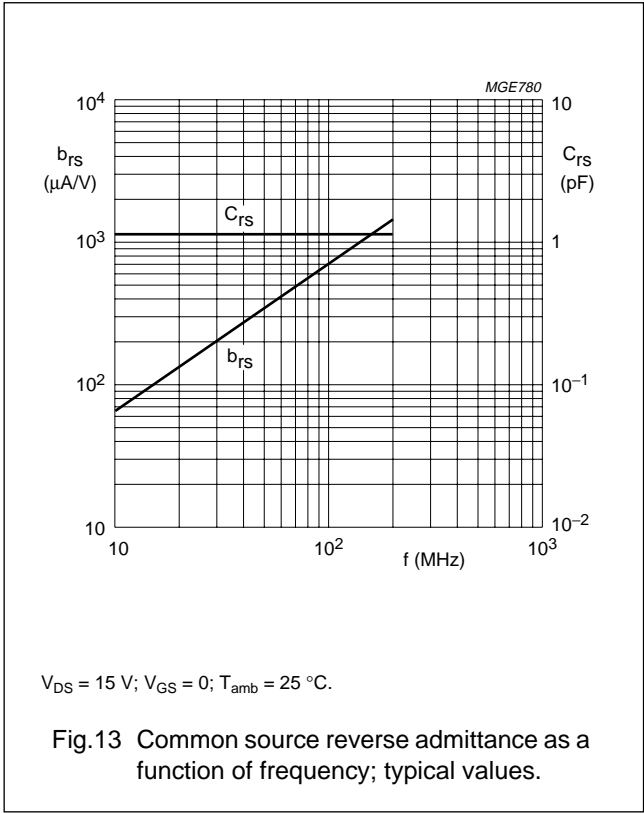
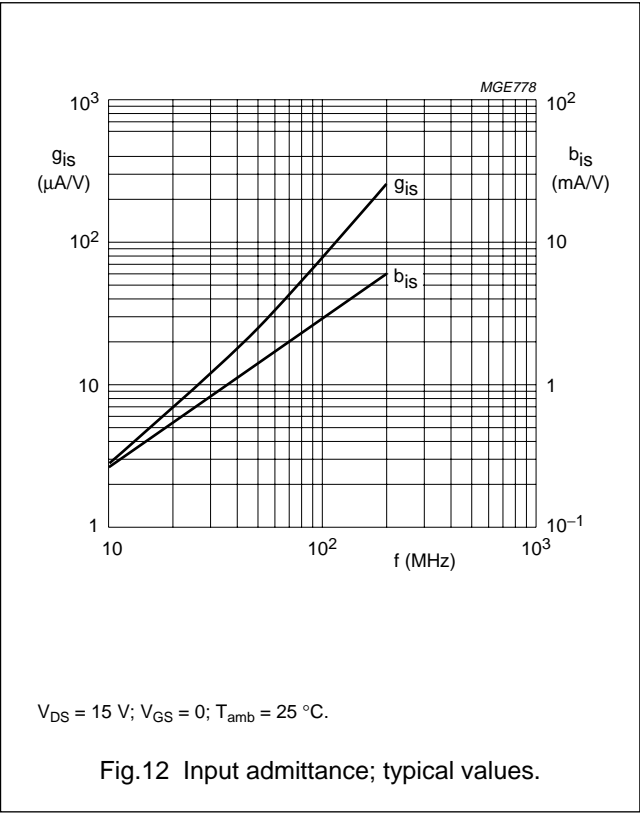


$V_{DS} = 15\text{ V}$.

Fig.11 Drain current as a function of junction temperature; typical values for BF245C.

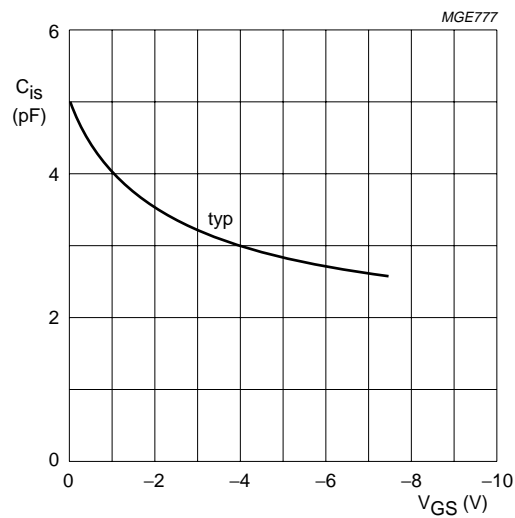
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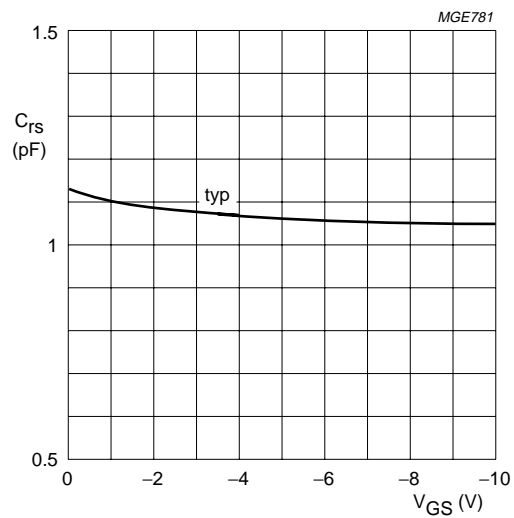
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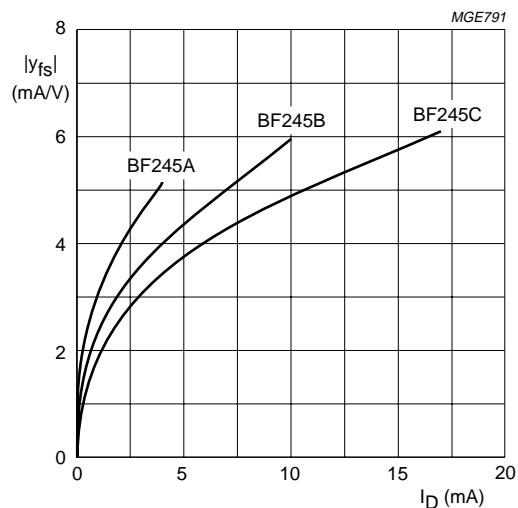
$V_{DS} = 20\text{ V}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Fig.16 Input capacitance as a function of gate-source voltage; typical values.



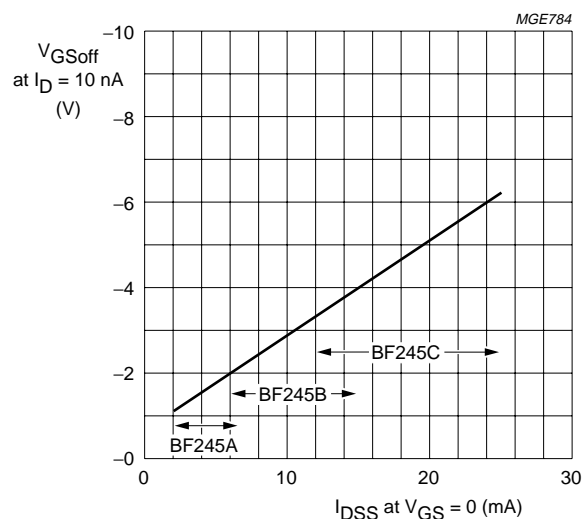
$V_{DS} = 20\text{ V}$; $f = 1\text{ MHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Fig.17 Reverse transfer capacitance as a function of gate-source voltage; typical values.



$V_{DS} = 15\text{ V}$; $f = 1\text{ kHz}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.

Fig.18 Forward transfer admittance as a function of drain current; typical values.



$V_{DS} = 15\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$.

Fig.19 Gate-source cut-off voltage as a function of drain current; typical values.

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